

REMARKS

Claims 1, 2 and 18-28 are presented for consideration, with Claims 1 and 28 being independent.

Independent Claim 1 has been amended to further distinguish Applicants' invention from the cited art. In addition, editorial changes have been made to selected claims, and new Claims 23-28 have been added to provide an additional scope of protection. Non-elected Claims 3-17 have been cancelled.

The abstract has been amended to better set forth the technical features of Applicants' invention.

Claims 1, 18, 19, 21 and 22 stand rejected under 35 U.S.C. §102(b) as allegedly being anticipated by Lehrer. Claim 2 is rejected under 35 U.S.C. §103 as allegedly being obvious over Lehrer. Finally, Claim 20 is rejected as allegedly being obvious over Lehrer in combination with Vogeli '954. These rejections are respectfully traversed.

Claim 1 of Applicants' invention relates to a method of manufacturing a dot pattern, comprising the steps of preparing a structured material composed of a plurality of columnar members containing a first component and a region containing a second component different from the first component surrounding the columnar members, with the structured material being formed by depositing the first component and the second component on a substrate, and removing the columnar members from the structured material to form a porous material having a columnar hole. In addition, a mask material is introduced into the columnar hole of the porous material to form a dot pattern, and the porous material is removed.

Support for the amendments to Claim 1, can be found, for example, on page 17, line 6, *et. seq.*, of the specification. In accordance with Applicants' claimed invention, a high performance method of manufacturing a dot pattern is provided.

The primary citation to Lehrer relates to fabrication of an integrated circuit formed of a substrate 1, an overlying etchable layer 2 and a mask 3 (Figure 1). The mask can first be removed (Figure 3A), or alternatively a metallic layer 7 is formed and then the mask is removed (Figure 3B). Exposed portions 8 of the insulating layer 2 are etched to achieve the desired structure shown in Figure 5. In contrast to Applicants' claimed invention, however, Lehrer does not teach or suggest, among other features, forming the structured material by depositing first and second components on a substrate. Instead, Lehrer relies on a photolithographic process as discussed above.

Accordingly, it is submitted that Lehrer fails to anticipate or render obvious Applicants' invention as set forth in Claim 1, and therefore reconsideration and withdrawal of the rejections of the claims under 35 U.S.C. §102 and §103 based on Lehrer are respectfully requested.

The secondary citation to Vogeli relates to a solar cell array and is relied upon for showing of electrodeposition. Vogeli fails, however, to compensate for the deficiencies in Lehrer as discussed above with respect to Applicants' Claim 1. The proposed combination of art, therefore, even if proper, still fails to teach or suggest Applicants' claimed invention. Reconsideration and withdrawal of the rejection of Claim 20 under 35 U.S.C. §103 is therefore respectfully requested.

Accordingly, it is submitted that Applicants' invention as set forth in independent Claim 1 is patentable over the cited art. In addition, dependent Claims 2 and 18-27 set forth additional features of Applicants' invention. Independent consideration of the dependent claims is respectfully requested.

Independent Claim 28 is also submitted to be patentable. Claim 28 relates to a method of manufacturing a dot pattern, and includes the steps of preparing a structured material composed of a plurality of columnar members containing a first component and a region containing a second component different from the first component surrounding the columnar members, removing the columnar members from the structured material to form a porous material having a columnar hole, and introducing material into the columnar hole portions of the porous material to form a dot pattern. In addition, the porous material is removed. In Claim 28, the structured material is formed by sputtering the first component and the second component on a substrate.

SECOND SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

In compliance with the duty of disclosure under 37 C.F.R. § 1.56 and in accordance with the practice under 37 C.F.R. §§ 1.97 and 1.98, the Examiner's attention is directed to the documents listed on the enclosed Form PTO-1449. Copies of the listed foreign documents are also enclosed.

The Examiner's attention is also directed to the following U.S. Applications:

<u>INVENTOR(S)</u>	<u>APPLICATION NO.</u>	<u>FILING DATE</u>
Shigeru Ichihara, et al.	10/912,082	August 6, 2004

The concise explanations of relevance for the non-English documents are provided by their accompanying English-language abstracts.

For the Examiner's information, U.S. Patent No. 5,068,152 corresponds to Japanese Document No. 2-139714, and U.S. Patent Appln. Publication No. 2004/0166376 and U.S. Patent No. 6,730,421 relate to Japanese Document No. 2000-327491.

It is respectfully requested that the above information be considered by the Examiner and that an initialed copy of the enclosed Form PTO-1449 be returned indicating that such information has been considered.

The fee in the amount of \$180.00 pursuant to 37 C.F.R. §1.97(c) and §1.17(p) is being paid electronically.

CONCLUSION

In view of the foregoing, reconsideration and allowance of this application is deemed to be in order and such action is respectfully requested.

Applicants' undersigned attorney may be reached in our Washington, D.C. office by telephone at (202) 530-1010. All correspondence should continue to be directed to our below-listed address.

Respectfully submitted,

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